

F. L. C. Riano and F. Rangel de Sousa

Radio Frequency Laboratory Department of Electrical and Electronics Engineering Federal University of Santa Catarina 88040-900 Florianópolis-SC, Brazil. fernando.rangel.sousa@ufsc.br

Chip Identification

- Ref.nr. : 77839/I03020/01
- Serv.Center: IMEC
- Technology: TSMC 180 nm CMOS Logic or MS/RF(mini@sic)
- Run nr.: 5839
- Subm.Date: 2017/9
- Topcell/Project name: LRF_UFSC_2017

Description

The integrated circuit is a 1-GHz ring oscillator designed in a differential topology, fabricated in the TSMC 180 nm MS/RF CMOS technology. In addition to the main oscillator, accessory circuits were included for easier testing. Notably, a narrowband phase locked loop was included to stabilize the carrier frequency, as well as a 50- Ω buffer for interfacing with 50- Ω equipment. The purpose of the designed oscillator is to provide a stable signal to a miniaturized wireless power transfer system envisaged to supply energy to implanted circuits.

The chip was assembled on the

surface of a printed circuit board using a FR4 substrate, Ohm). The connections were done with gold wires, using a wire-bonding machine.

Chip Photography

Photography of the PCB



RF

Experimental setup and Results

Two DC power supplies were used to provide energy to the circuit. The oscillator was powered with 1,5 V and the buffer and additional circuits used 1,8 V. The test board was designed as a shield to an Altera DE-2 FPGA development board. A digital circuit was synthesized on FPGA to provide the control signals necessary to configure the oscillator. A spectrum analyzer was used to verify the oscillator output signal.

The circuit oscillated at 1.14 GHz and the measure power was -8.5 dBm. This output is very close to the results predicted from post layout simulations..

A new testbench is being developed to measure the oscillator phase noise and explore it in the target application.



